Silicon N-Channel MOS FET

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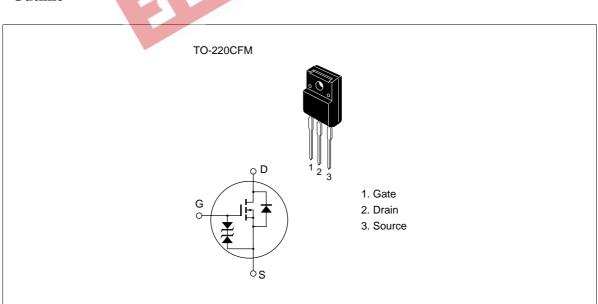
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for Switching regulator

Outline





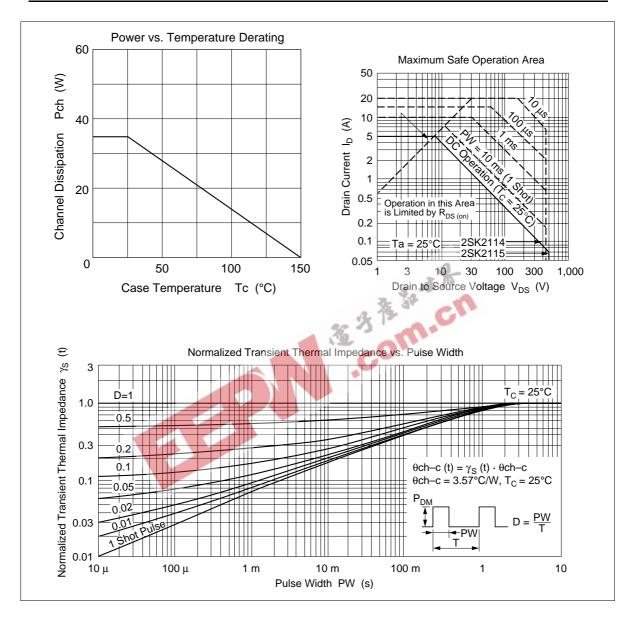
Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item		Symbol	Ratings	Unit	
Drain to source voltage	2SK2114	V _{DSS}	450	V	
	2SK2115	V _{DSS}	500		
Gate to source voltage		V _{GSS}	±30	V	
Drain current		I _D	5	A	
Drain peak current		I D(pulse) *1	20	A	
Body to drain diode reverse drain cu	irrent	I _{DR}	5	A	
Channel dissipation	Pch*2	35	W		
Channel temperature	Tch	150	°C		
Storage temperature		Tstg	-55 to +150	°C	
2. Value at Tc = 25 °C		·爱考节 · C	-55 to +150		

Electrical Characteristics (Ta = 25°C)

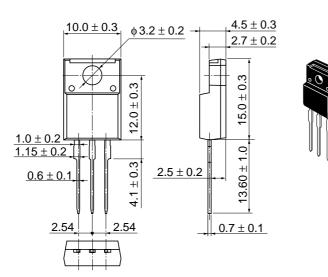
Item		Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source	2SK2114	$V_{(BR)DSS}$	450	_	—	V	$I_{\rm D} = 10 \text{ mA}, V_{\rm GS} = 0$
breakdown voltage	2SK2115	_	500				
Gate to source br voltage	eakdown	$V_{(BR)GSS}$	±30	_	_	V	$I_{\rm G}=\pm100~\mu\text{A},~V_{\rm DS}=0$
Gate to source le	ak current	I _{GSS}	—		±10	μA	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate	2SK2114	I _{DSS}	_		250	μA	$V_{DS} = 360 \text{ V}, \text{ V}_{GS} = 0$
voltage drain current	2SK2115	_					$V_{\rm DS} = 400 \ V, \ V_{\rm GS} = 0$
Gate to source cu	utoff voltage	$V_{GS(off)}$	2.0	—	3.0	V	$I_{\rm D}$ = 1 mA, $V_{\rm DS}$ = 10 V
Static drain to	2SK2114	R _{DS(on)}	_	1.0	1.4	Ω	$I_{\rm D} = 2.5 \text{ A}, V_{\rm GS} = 10 \text{ V}^{*1}$
source on state resistance	2SK2115	_	_	1.2	1.5	392.38	20
Forward transfer	admittance	y _{fs}	2.5	4.0	1	S	$I_{\rm D} = 2.5 \text{ A}$ $V_{\rm DS} = 10 \text{ V}^{*1}$
Input capacitance	9	Ciss	-	640	-07	pF	V _{DS} = 10 V
Output capacitan	се	Coss	-AL I	160	-	pF	$V_{GS} = 0$
Reverse transfer	capacitance	Crss	ZJ	20	_	pF	f = 1 MHz
Turn-on delay tim	ne	t _{d(on)}	-	10	_	ns	I _D = 2.5 A
Rise time		t,	_	25	_	ns	V _{GS} = 10 V
Turn-off delay tim	ne	t _{d(off)}	_	50	_	ns	R_= 12 Ω
Fall time		t _f	_	30	_	ns	_
Body to drain dio voltage	de forward	V_{DF}	_	0.95	_	V	$I_{\rm F} = 5 \text{ A}, V_{\rm GS} = 0$
Body to drain dio recovery time	de reverse	t _{rr}	—	300		ns	$I_{_{\rm F}} = 5 \text{ A}, V_{_{\rm GS}} = 0,$ $di_{_{\rm F}} / dt = 100 \text{ A} / \mu \text{s}$

See characteristics curve of 2SK1155, 2SK1156.









Hitachi Code	TO-220CFM
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Weight (reference value)	1.9 g

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